



**AAEON Technology INC.**  
ISO-9001/ISO-14001 Certified  
Industrial Automation PCs

# **GENE-4310**

## **Thermal Image Analysis Report**

**Release Date: JUNE.29, 2000**

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**Issue Stamp**

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**QA Manager**

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**QE Manager**

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**Test Engineer**

# Thermal Image Analysis

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**I . Model Name: GENE-4310**

**II . Description: NS Geode GXLV SubCompact Board with LCD, LVDS, Ethernet, & Audio**

**III . Date: JUNE. 29, 2000**

**IV. Measure Site: AAEON QE Dept.**

**V. Issied by : Fenglin Dong**

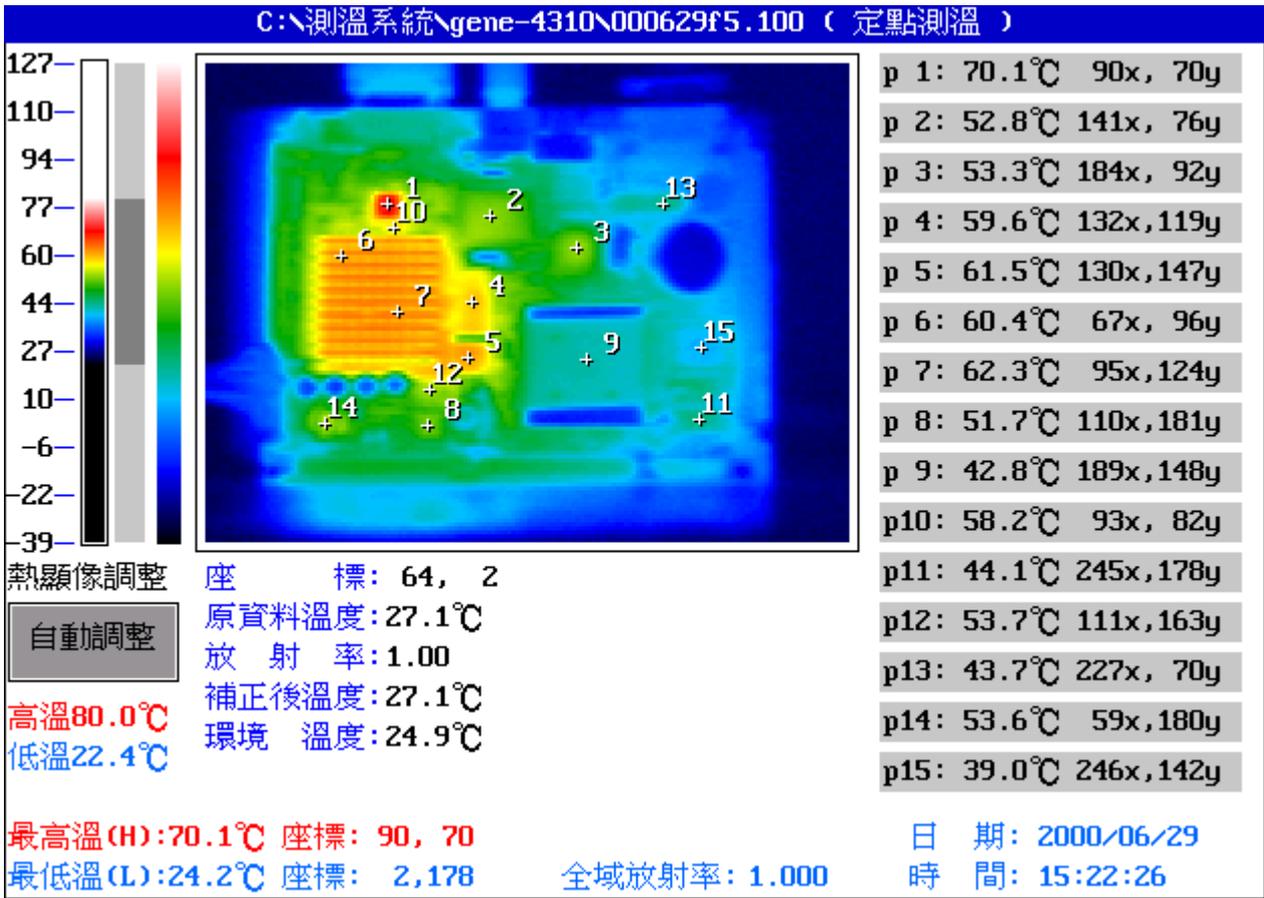
**VI.Equipment: TVS-100 series by NIPPON AVIONICS CO., LTD.**

**VII. Simulation Environment:**

- **Temperature: 24.9 degrees C**
- **CPU: P 233 (On Board)**
- **Memory: Compact Flush**
- **RAM: 32 MB (NEC D4564163G5-A10-9JF)**
- **Application Software: QAPLUS/FE V5.2**
- **Take Picture Time: Power on 30 minutes after**

## VIII. Prediction Result:

### 1. Component Side:



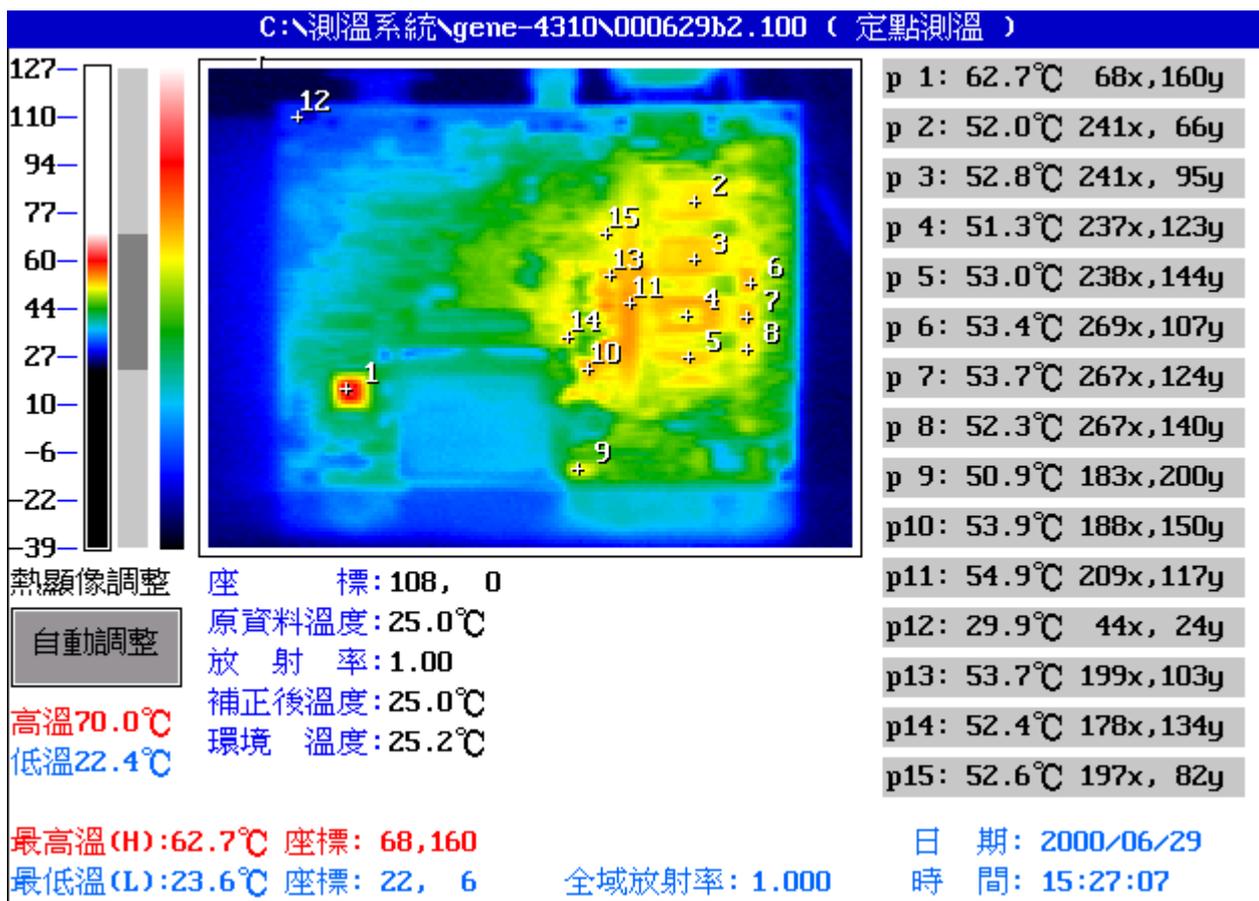
Point	Position	Describe	Ts	Tm	Note
1	U10	ANDEV, AD1819BJST	70	70.1	※ = -35.1
2	U3	Winbond, W83977F-A	70	52.8	
3	U22	Intel 82559		53.3	
4	U25	ICS, MK1491-06	70	59.6	※ = -24.6
5	Q6	LINFINY, LX8384-00CDDT	70	62.5	※ = -27.5
6	U1	ACE, ACE-CM260-363515	70	60.4	※ = -25.4
7	U1	ACE, ACE-CM260-363515	70	62.3	※ = -27.3
8	U13	W83781D	70	51.7	※ = -16.7
9	U2	N.S, CS5530	70	42.8	※ = -7.8
10	---				
11	U18	Thine TI000320	70	44.1	※ = -9.1
12	CT20	EC, 1000 μ F, 6.3V, 20% 8*11mm, DIP	70	53.7	※ = -18.7
13	U4	HARRIS, HIN213CA	75	43.7	※ = -8.7
14	---				
15	U21	29EE010	70	39.0	※ = -4

#### 1. Operation Temperature (°C):

Ts = Defined by component specification ; Tm = Measured by QE

#### 2. ※ = Ts - (Tm + 60 - 25)

## 2. Solder Side:



Point	Position	Describe	Ts	Tm	Note
1	U19	74F373D	70	62.7	※
2	RAM		-	52.0	
3	RAM		-	52.8	
4	RAM		-	51.3	
5	RAM		-	53.0	
6	---				
7	---				
8	---				
9	U6	PHILIPS, N74F14DT	70	50.9	※
10	---				
11	---				
12	---				
13	---				
14	---				
15	---				

### 1. Operation Temperature (°C):

Ts = Defined by component specification ; Tm = Measured by QE

2. ※ = Ts - (Tm + 60 - 25)